

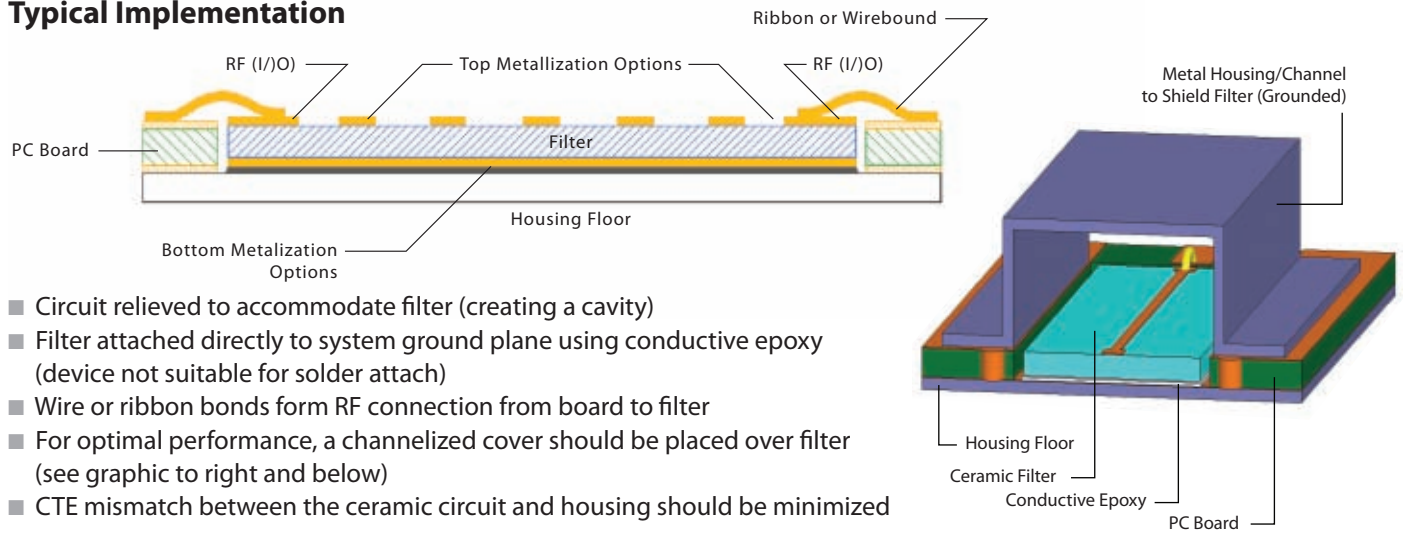
DLI Epoxy Mount - Chip and Wire Filters Application Note



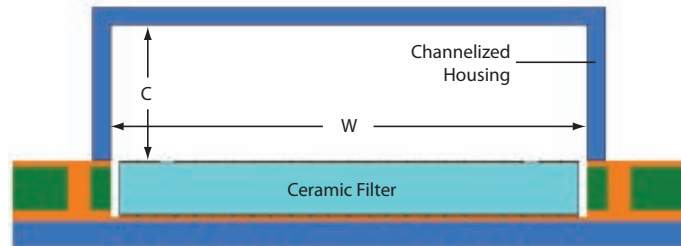
Applications and System Packaging

- Aluminum housings
- LTCC and HTCC modules
- Kovar MMIC hermetic modules

Typical Implementation



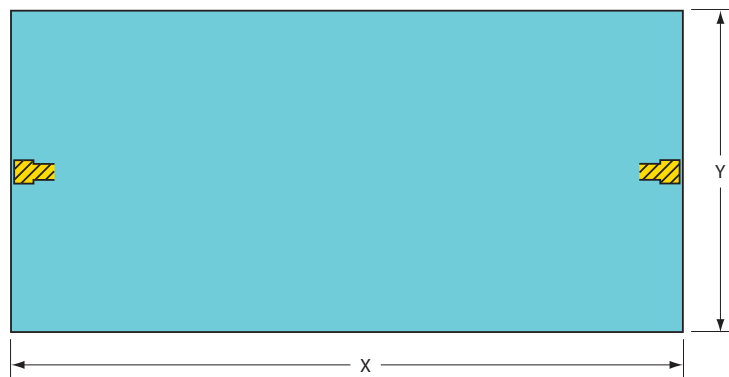
- Circuit relieved to accommodate filter (creating a cavity)
- Filter attached directly to system ground plane using conductive epoxy (device not suitable for solder attach)
- Wire or ribbon bonds form RF connection from board to filter
- For optimal performance, a channelized cover should be placed over filter (see graphic to right and below)
- CTE mismatch between the ceramic circuit and housing should be minimized



C: Cover Height
W: Channel Width

Customers can state a desired cover height and channel width or DLI engineering can make a recommendation based on the filter design

Typical Layout (Filter Top Side)



- X and Y dimensions determined at time of final design
- Typical filter thickness: 15, 20 or 30 mils
- Centerline I/O location typical, but can vary per design
- I/O bond pads typically 10x10 mils

